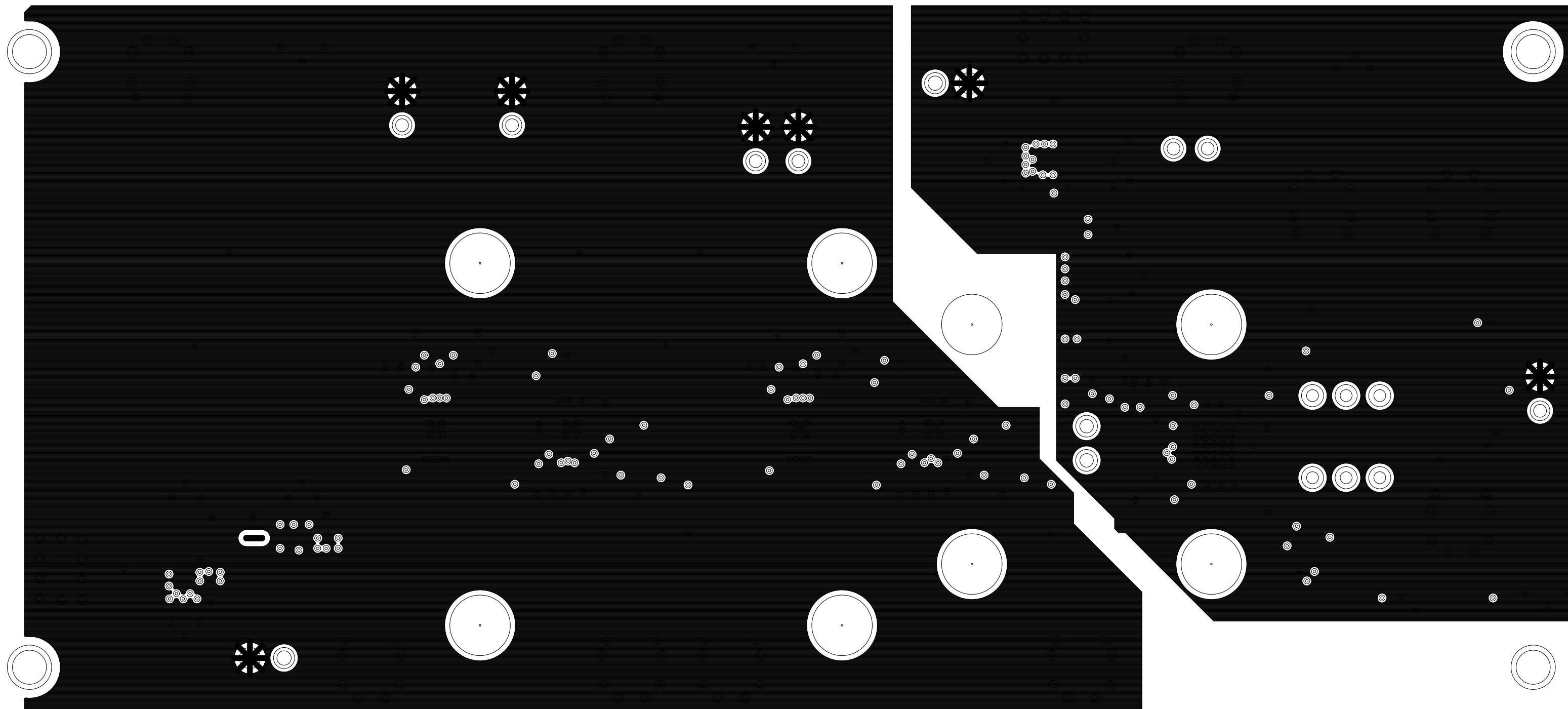
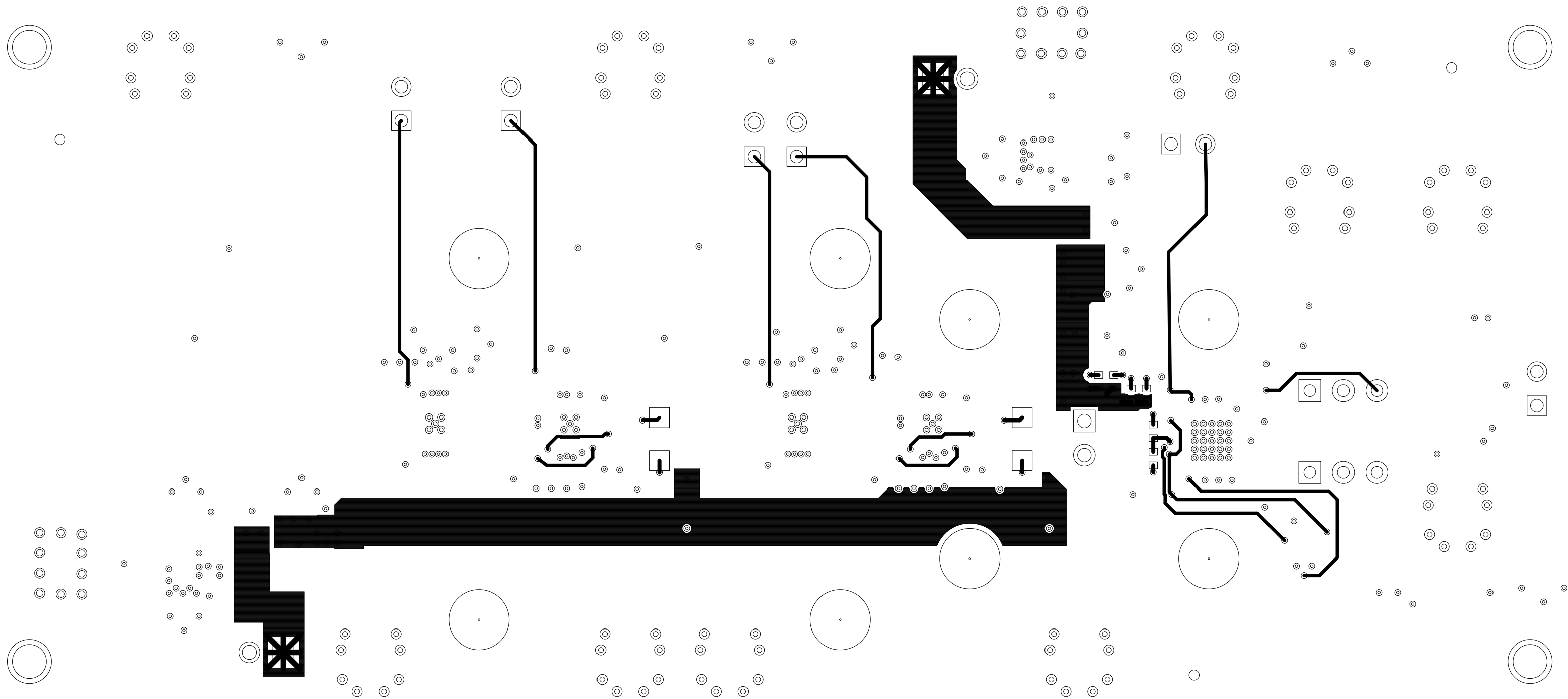


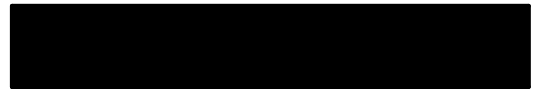
TIDA-01187 REV A
LAYER 1 (TOP SIDE)



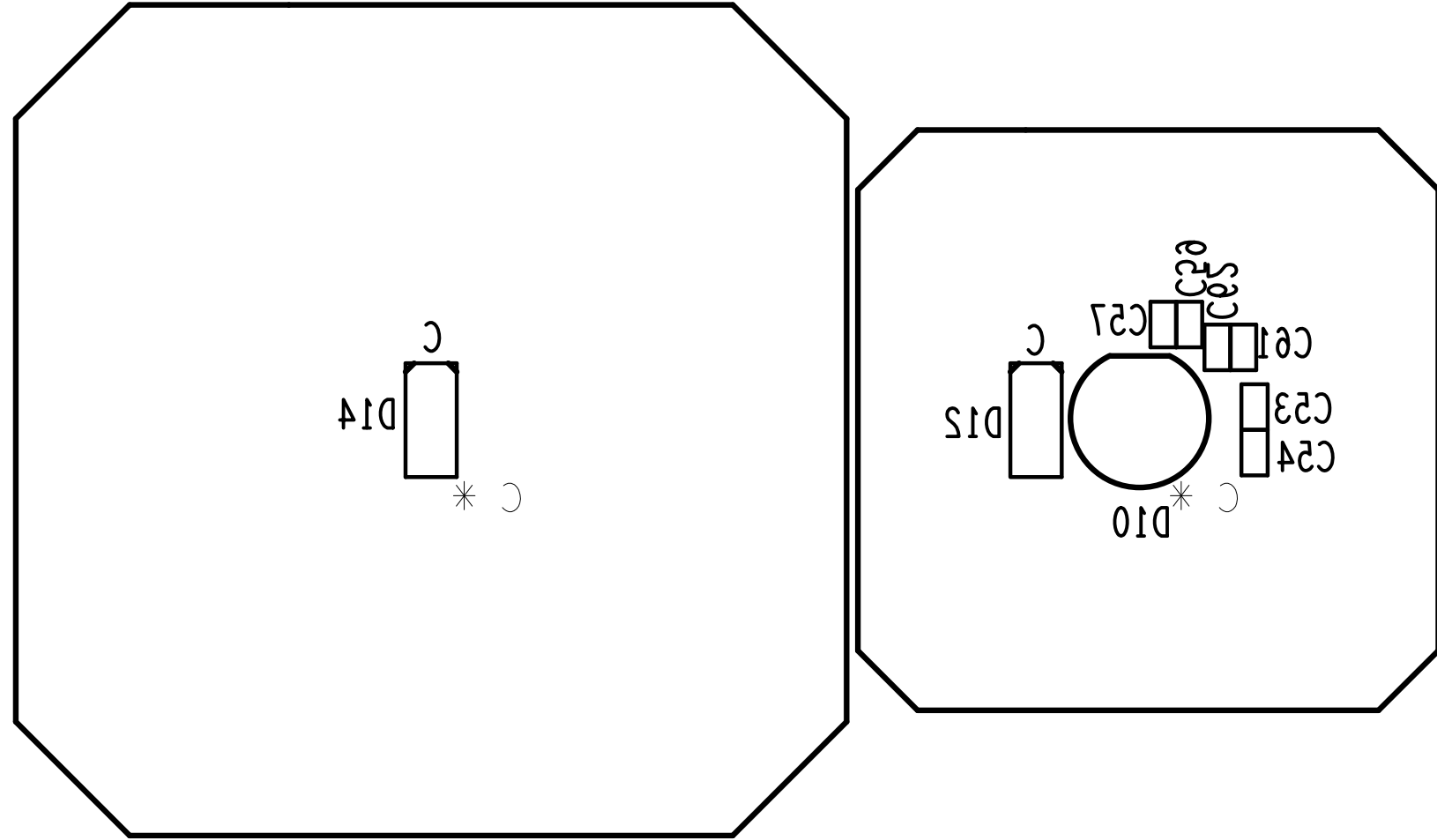
TIDA-01187 REV A
LAYER 2 - GROUND



TIDA-01187 REV A
LAYER 4 (BOTTOM SIDE)

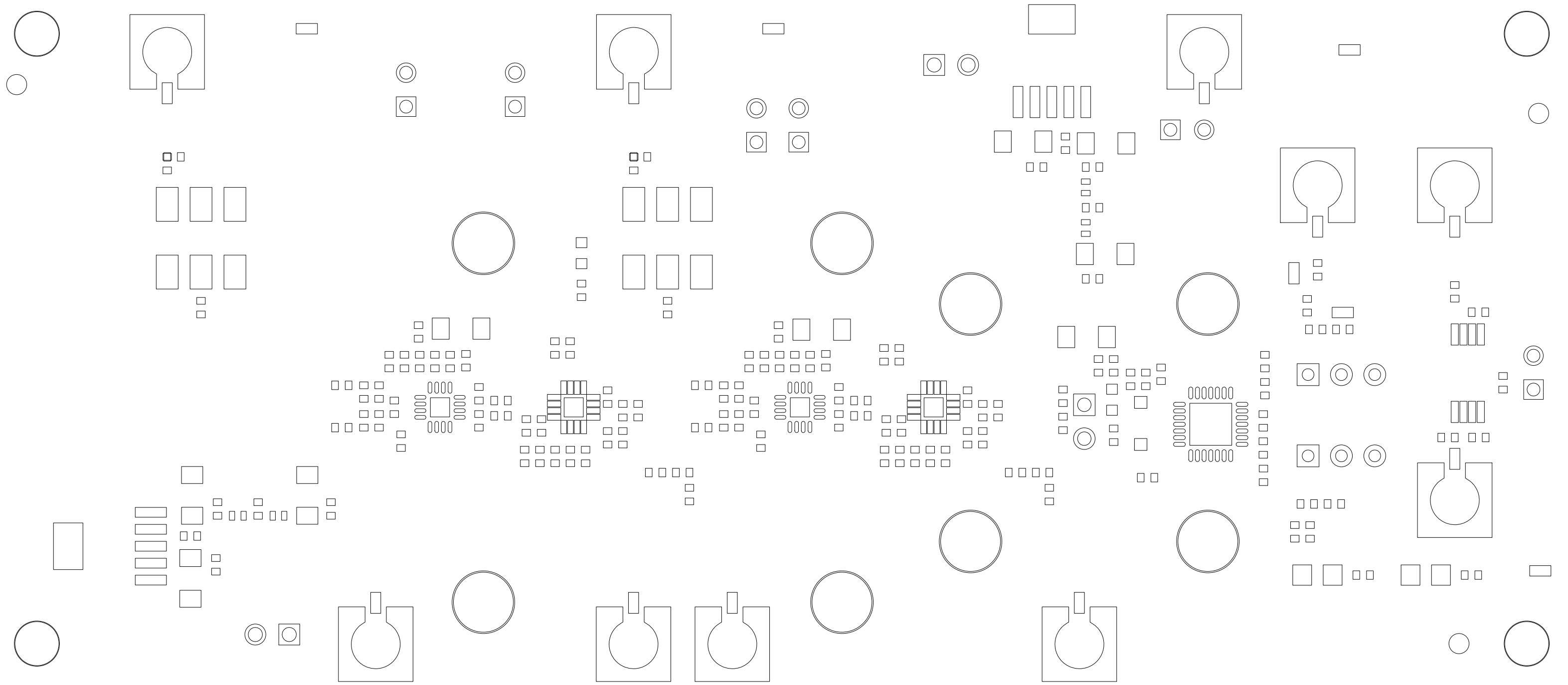


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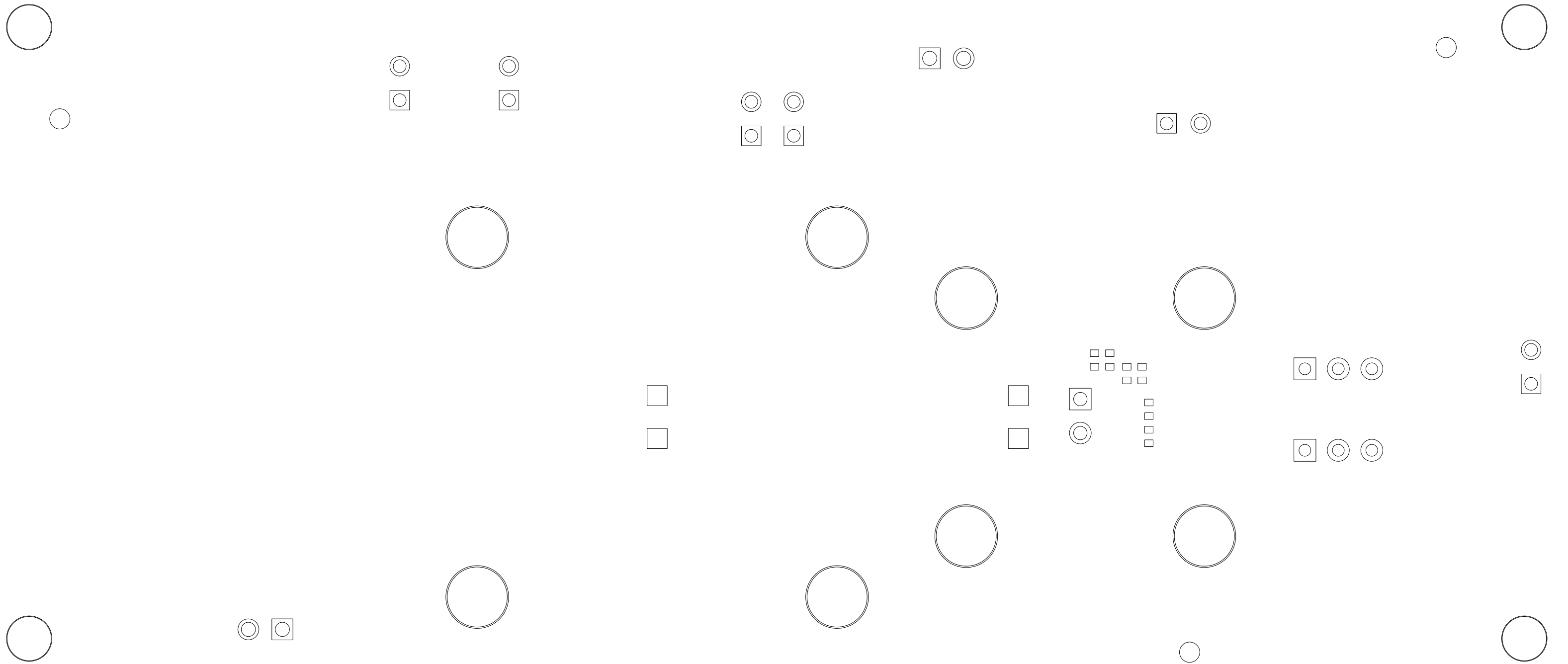


Made in U.S.A.

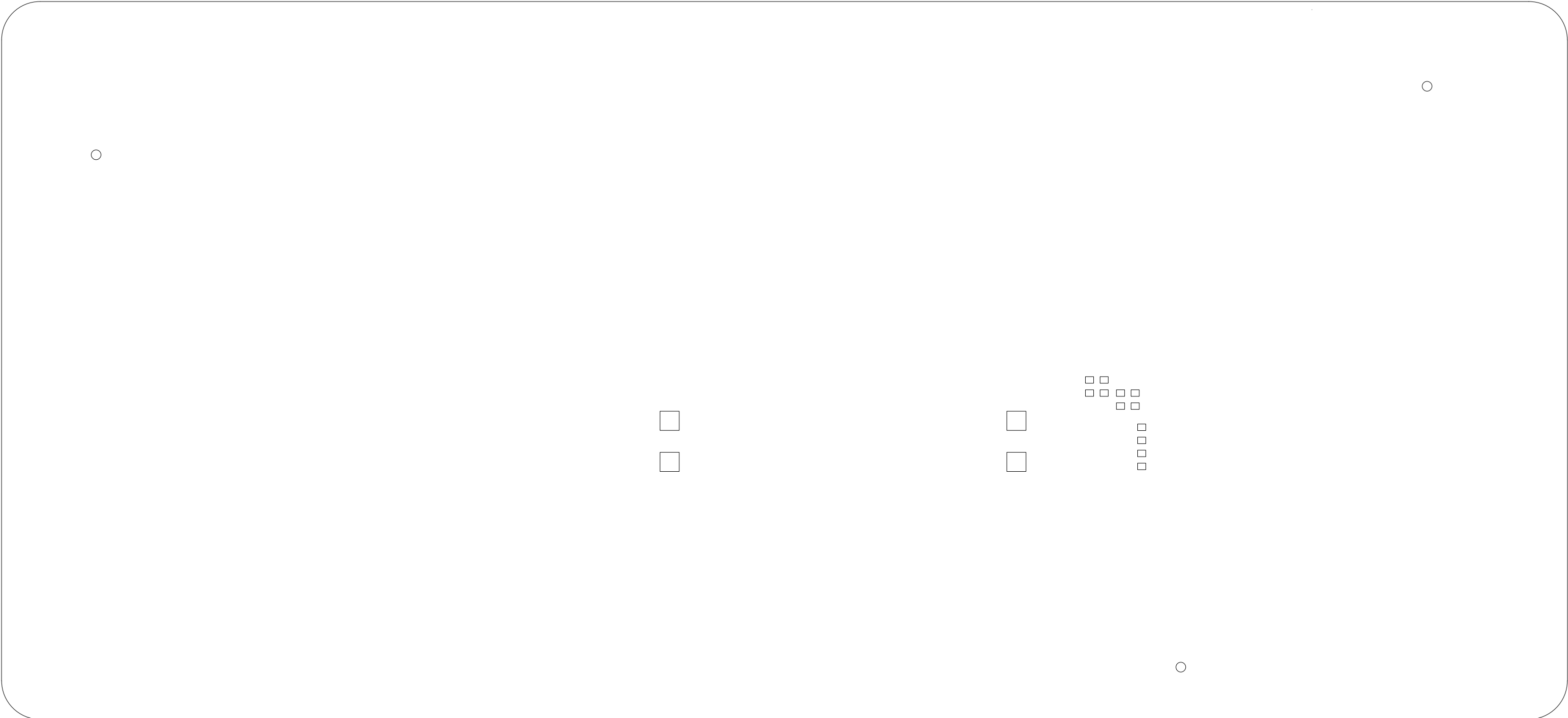
TIDA-01187 REV A
SILKSCREEN BOTTOM



TIDA-01187 REV A
SOLDERMASK TOP



TIDA-01187 REV A
SOLDERMASK BOTTOM



TIDA-01187 REV A
PASTEMASK BOTTOM

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